



Welcome to [E-XFL.COM](#)

What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	ARM® Cortex®-M4/M0
Core Size	32-Bit Dual-Core
Speed	204MHz
Connectivity	CANbus, EBI/EMI, I ² C, IrDA, Microwire, SD, SPI, SSI, SSP, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I ² S, Motor Control PWM, POR, PWM, WDT
Number of I/O	83
Program Memory Size	-
Program Memory Type	ROMless
EEPROM Size	-
RAM Size	168K x 8
Voltage - Supply (Vcc/Vdd)	2.2V ~ 3.6V
Data Converters	A/D 8x10b; D/A 1x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	144-LQFP
Supplier Device Package	144-LQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/lpc4310fbd144-551

Table 3. Pin description ...continuedLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
P1_5	R5	N3	J4	48	[2]	N; PU	I/O	GPIO1[8] — General purpose digital input/output pin.
							O	CTOUT_10 — SCTimer/PWM output 10. Match output 3 of timer 3.
							-	R — Function reserved.
							O	EMC_CS0 — LOW active Chip Select 0 signal.
							I	USB0_PWR_FAULT — Port power fault signal indicating overcurrent condition; this signal monitors over-current on the USB bus (external circuitry required to detect over-current condition).
							I/O	SSP1_SSEL — Slave Select for SSP1.
							I/O	SGPIO15 — General purpose digital input/output pin.
P1_6	T4	P3	K4	49	[2]	N; PU	O	SD_POW — SD/MMC power monitor output.
							I/O	GPIO1[9] — General purpose digital input/output pin.
							I	CTIN_5 — SCTimer/PWM input 5. Capture input 2 of timer 2.
							-	R — Function reserved.
							O	EMC_WE — LOW active Write Enable signal.
							-	R — Function reserved.
							-	R — Function reserved.
P1_7	T5	N4	G4	50	[2]	N; PU	I/O	SGPIO14 — General purpose digital input/output pin.
							I/O	SD_CMD — SD/MMC command signal.
							I/O	GPIO1[0] — General purpose digital input/output pin.
							I	U1_DSR — Data Set Ready input for UART1.
							O	CTOUT_13 — SCTimer/PWM output 13. Match output 3 of timer 3.
							I/O	EMC_D0 — External memory data line 0.
							O	USB0_PPWR — VBUS drive signal (towards external charge pump or power management unit); indicates that VBUS must be driven (active HIGH). Add a pull-down resistor to disable the power switch at reset. This signal has opposite polarity compared to the USB_PPWR used on other NXP LPC parts.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.

Table 3. Pin description ...continuedLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
P3_1	G11	D10	F7	114	[2]	N; PU	I/O	I2S0_TX_WS — Transmit Word Select. It is driven by the master and received by the slave. Corresponds to the signal WS in the <i>I²S-bus specification</i> .
							I/O	I2S0_RX_WS — Receive Word Select. It is driven by the master and received by the slave. Corresponds to the signal WS in the <i>I²S-bus specification</i> .
							I	CAN0_RD — CAN receiver input.
							O	USB1_IND1 — USB1 Port indicator LED control output 1.
							I/O	GPIO5[8] — General purpose digital input/output pin.
							-	R — Function reserved.
							O	LCD_VD15 — LCD data.
P3_2	F11	D9	G6	116	[2]	OL; PU	-	R — Function reserved.
							I/O	I2S0_TX_SDA — I2S transmit data. It is driven by the transmitter and read by the receiver. Corresponds to the signal SD in the <i>I²S-bus specification</i> .
							I/O	I2S0_RX_SDA — I2S Receive data. It is driven by the transmitter and read by the receiver. Corresponds to the signal SD in the <i>I²S-bus specification</i> .
							O	CAN0_TD — CAN transmitter output.
							O	USB1_IND0 — USB1 Port indicator LED control output 0.
							I/O	GPIO5[9] — General purpose digital input/output pin.
							-	R — Function reserved.
P3_3	B14	B13	A7	118	[4]	N; PU	O	LCD_VD14 — LCD data.
							-	R — Function reserved.
							-	R — Function reserved.
							I/O	SPI_SCK — Serial clock for SPI.
							I/O	SSP0_SCK — Serial clock for SSP0.
							O	SPIFI_SCK — Serial clock for SPIFI.
							O	CGU_OUT1 — CGU spare clock output 1.
							-	R — Function reserved.
							O	I2S0_TX_MCLK — I2S transmit master clock.
							I/O	I2S1_TX_SCK — Transmit Clock. It is driven by the master and received by the slave. Corresponds to the signal SCK in the <i>I²S-bus specification</i> .

Table 3. Pin description ...continuedLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
P4_2	D3	A2	-	8	[2]	N; PU	I/O	GPIO2[2] — General purpose digital input/output pin.
							O	CTOUT_0 — SCTimer/PWM output 0. Match output 0 of timer 0.
							O	LCD_VD3 — LCD data.
							-	R — Function reserved.
							-	R — Function reserved.
							O	LCD_VD12 — LCD data.
							I	U3_RXD — Receiver input for USART3.
							I/O	SGPIO8 — General purpose digital input/output pin.
P4_3	C2	B2	-	7	[5]	N; PU	I/O	GPIO2[3] — General purpose digital input/output pin.
							O	CTOUT_3 — SCTimer/PWM output 3. Match output 3 of timer 0.
							O	LCD_VD2 — LCD data.
							-	R — Function reserved.
							-	R — Function reserved.
							O	LCD_VD21 — LCD data.
							I/O	U3_BAUD — Baud pin for USART3.
							I/O	SGPIO9 — General purpose digital input/output pin.
P4_4	B1	A1	-	9	[5]	N; PU	AI	ADC0_0 — DAC output; ADC0 and ADC1, input channel 0. Configure the pin as GPIO input and use the ADC function select register in the SCU to select the ADC.
							I/O	GPIO2[4] — General purpose digital input/output pin.
							O	CTOUT_2 — SCTimer/PWM output 2. Match output 2 of timer 0.
							O	LCD_VD1 — LCD data.
							-	R — Function reserved.
							-	R — Function reserved.
							O	LCD_VD20 — LCD data.
							I/O	U3_DIR — RS-485/EIA-485 output enable/direction control for USART3.
							I/O	SGPIO10 — General purpose digital input/output pin.
							O	DAC — DAC output. Shared between 10-bit ADC0/1 and DAC.. Configure the pin as GPIO input and use the analog function select register in the SCU to select the DAC.

Table 3. Pin description ...continuedLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
P4_5	D2	C2	-	10	[2]	N; PU	I/O	GPIO2[5] — General purpose digital input/output pin.
							O	CTOUT_5 — SCTimer/PWM output 5. Match output 3 of timer 3.
							O	LCD_FP — Frame pulse (STN). Vertical synchronization pulse (TFT).
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
P4_6	C1	B1	-	11	[2]	N; PU	I/O	SGPIO11 — General purpose digital input/output pin.
							O	CTOUT_4 — SCTimer/PWM output 4. Match output 3 of timer 3.
							O	LCD_ENAB/LCDM — STN AC bias drive or TFT data enable input.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
P4_7	H4	F4	-	14	[2]	O; PU	I/O	SGPIO12 — General purpose digital input/output pin.
							O	LCD_DCLK — LCD panel clock.
							I	GP_CLKIN — General-purpose clock input to the CGU.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
P4_8	E2	D2	-	15	[2]	N; PU	I/O	I2S1_TX_SCK — Transmit Clock. It is driven by the master and received by the slave. Corresponds to the signal SCK in the I ² S-bus specification.
							I/O	I2S0_TX_SCK — Transmit Clock. It is driven by the master and received by the slave. Corresponds to the signal SCK in the I ² S-bus specification.
							-	R — Function reserved.
							I	CTIN_5 — SCTimer/PWM input 5. Capture input 2 of timer 2.
							O	LCD_VD9 — LCD data.
							-	R — Function reserved.
							I/O	GPIO5[12] — General purpose digital input/output pin.
							O	LCD_VD22 — LCD data.
							O	CAN1_TD — CAN1 transmitter output.
							I/O	SGPIO13 — General purpose digital input/output pin.

Table 3. Pin description ...continuedLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
P8_3	J3	H3	-	-	[2]	N; PU	I/O	GPIO4[3] — General purpose digital input/output pin.
							I/O	USB1_ULPI_D2 — ULPI link bidirectional data line 2.
							-	R — Function reserved.
							O	LCD_VD12 — LCD data.
							O	LCD_VD19 — LCD data.
							-	R — Function reserved.
							-	R — Function reserved.
							O	T0_MAT3 — Match output 3 of timer 0.
P8_4	J2	H2	-	-	[2]	N; PU	I/O	GPIO4[4] — General purpose digital input/output pin.
							I/O	USB1_ULPI_D1 — ULPI link bidirectional data line 1.
							-	R — Function reserved.
							O	LCD_VD7 — LCD data.
							O	LCD_VD16 — LCD data.
							-	R — Function reserved.
							-	R — Function reserved.
P8_5	J1	H1	-	-	[2]	N; PU	I/O	GPIO4[5] — General purpose digital input/output pin.
							I/O	USB1_ULPI_D0 — ULPI link bidirectional data line 0.
							-	R — Function reserved.
							O	LCD_VD6 — LCD data.
							O	LCD_VD8 — LCD data.
							-	R — Function reserved.
							-	R — Function reserved.
P8_6	K3	J3	-	-	[2]	N; PU	I/O	GPIO4[6] — General purpose digital input/output pin.
							I	USB1_ULPI_NXT — ULPI link NXT signal. Data flow control signal from the PHY.
							-	R — Function reserved.
							O	LCD_VD5 — LCD data.
							O	LCD_LP — Line synchronization pulse (STN). Horizontal synchronization pulse (TFT).
							-	R — Function reserved.
							-	R — Function reserved.
P8_6	K3	J3	-	-	[2]	N; PU	I	T0_CAP2 — Capture input 2 of timer 0.

Table 3. Pin description ...continuedLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
PE_3	K12	K10	-	-	[2]	N; PU	-	R — Function reserved.
							O	CAN0_TD — CAN transmitter output.
							I	ADCTRIG1 — ADC trigger input 1.
							I/O	EMC_A21 — External memory address line 21.
							I/O	GPIO7[3] — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
PE_4	K13	J11	-	-	[2]	N; PU	-	R — Function reserved.
							I	NMI — External interrupt input to NMI.
							-	R — Function reserved.
							I/O	EMC_A22 — External memory address line 22.
							I/O	GPIO7[4] — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
PE_5	N16	-	-	-	[2]	N; PU	-	R — Function reserved.
							O	CTOUT_3 — SCTimer/PWM output 3. Match output 3 of timer 0.
							O	U1_RTS — Request to Send output for UART 1. Can also be configured to be an RS-485/EIA-485 output enable signal for UART 1.
							I/O	EMC_D24 — External memory data line 24.
							I/O	GPIO7[5] — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
PE_6	M16	-	-	-	[2]	N; PU	-	R — Function reserved.
							O	CTOUT_2 — SCTimer/PWM output 2. Match output 2 of timer 0.
							I	U1_RI — Ring Indicator input for UART 1.
							I/O	EMC_D25 — External memory data line 25.
							I/O	GPIO7[6] — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.

Table 3. Pin description ...continuedLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
PE_15	E13	-	-	-	[2]	N; PU	-	R — Function reserved.
							O	CTOUT_0 — SCTimer/PWM output 0. Match output 0 of timer 0.
							I/O	I2C1_SCL — I ² C1 clock input/output (this pin does not use a specialized I2C pad).
							O	EMC_CKEOUT3 — SDRAM clock enable 3.
							I/O	GPIO7[15] — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
PF_0	D12	-	-	-	[2]	O; PU	I/O	SSP0_SCK — Serial clock for SSP0.
							I	GP_CLKIN — General-purpose clock input to the CGU.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							O	I2S1_TX_MCLK — I2S1 transmit master clock.
PF_1	E11	-	-	-	[2]	N; PU	-	R — Function reserved.
							-	R — Function reserved.
							I/O	SSP0_SSEL — Slave Select for SSP0.
							-	R — Function reserved.
							I/O	GPIO7[16] — General purpose digital input/output pin.
							-	R — Function reserved.
							I/O	SGPIO0 — General purpose digital input/output pin.
PF_2	D11	-	-	-	[2]	N; PU	-	R — Function reserved.
							O	U3_TXD — Transmitter output for USART3.
							I/O	SSP0_MISO — Master In Slave Out for SSP0.
							-	R — Function reserved.
							I/O	GPIO7[17] — General purpose digital input/output pin.
							-	R — Function reserved.
							I/O	SGPIO1 — General purpose digital input/output pin.
							-	R — Function reserved.

Table 3. Pin description ...continuedLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
PF_3	E10	-	-	-	[2]	N; PU	-	R — Function reserved.
							I	U3_RXD — Receiver input for USART3.
							I/O	SSP0_MOSI — Master Out Slave in for SSP0.
							-	R — Function reserved.
							I/O	GPIO7[18] — General purpose digital input/output pin.
							-	R — Function reserved.
							I/O	SGPIO2 — General purpose digital input/output pin.
							-	R — Function reserved.
PF_4	D10	D6	H4	120	[2]	O; PU	I/O	SSP1_SCK — Serial clock for SSP1.
							I	GP_CLKIN — General-purpose clock input to the CGU.
							O	TRACECLK — Trace clock.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							O	I2S0_TX_MCLK — I2S transmit master clock.
							I/O	I2S0_RX_SCK — I2S receive clock. It is driven by the master and received by the slave. Corresponds to the signal SCK in the <i>I²S-bus specification</i> .
PF_5	E9	-	-	-	[5]	N; PU	-	R — Function reserved.
							I/O	U3_UCLK — Serial clock input/output for USART3 in synchronous mode.
							I/O	SSP1_SSEL — Slave Select for SSP1.
							O	TRACEDATA[0] — Trace data, bit 0.
							I/O	GPIO7[19] — General purpose digital input/output pin.
							-	R — Function reserved.
							I/O	SGPIO4 — General purpose digital input/output pin.
							-	R — Function reserved.
AI							AI	ADC1_4 — ADC1 and ADC0, input channel 4. Configure the pin as GPIO input and use the ADC function select register in the SCU to select the ADC.

Table 3. Pin description ...continuedLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
WAKEUP1	A10	C8	-	-	[11]	I; IA	I	External wake-up input; can raise an interrupt and can cause wake-up from any of the low-power modes. A pulse with a duration > 45 ns wakes up the part. This pin does not have an internal pull-up.
WAKEUP2	C9	E5	-	-	[11]	I; IA	I	External wake-up input; can raise an interrupt and can cause wake-up from any of the low-power modes. A pulse with a duration > 45 ns wakes up the part. This pin does not have an internal pull-up.
WAKEUP3	D8	-	-	-	[11]	I; IA	I	External wake-up input; can raise an interrupt and can cause wake-up from any of the low-power modes. A pulse with a duration > 45 ns wakes up the part. This pin does not have an internal pull-up.
ADC pins								
ADC0_0/ ADC1_0/DAC	E3	B6	A2	6	[8]	I; IA	I	ADC input channel 0. Shared between 10-bit ADC0/1 and DAC.
ADC0_1/ ADC1_1	C3	C4	A1	2	[8]	I; IA	I	ADC input channel 1. Shared between 10-bit ADC0/1.
ADC0_2/ ADC1_2	A4	B3	B3	143	[8]	I; IA	I	ADC input channel 2. Shared between 10-bit ADC0/1.
ADC0_3/ ADC1_3	B5	B4	A3	139	[8]	I; IA	I	ADC input channel 3. Shared between 10-bit ADC0/1.
ADC0_4/ ADC1_4	C6	A5	-	138	[8]	I; IA	I	ADC input channel 4. Shared between 10-bit ADC0/1.
ADC0_5/ ADC1_5	B3	C3	-	144	[8]	I; IA	I	ADC input channel 5. Shared between 10-bit ADC0/1.
ADC0_6/ ADC1_6	A5	A4	-	142	[8]	I; IA	I	ADC input channel 6. Shared between 10-bit ADC0/1.
ADC0_7/ ADC1_7	C5	B5	-	136	[8]	I; IA	I	ADC input channel 7. Shared between 10-bit ADC0/1.
RTC								
RTC_ALARM	A11	A10	C3	129	[11]	O	O	RTC controlled output. This pin has an internal pull-up. The reset state of this pin is LOW after POR. For all other types of reset, the reset state depends on the state of the RTC alarm interrupt.
RTCX1	A8	A8	A5	125	[8]	-	I	Input to the RTC 32 kHz ultra-low power oscillator circuit.
RTCX2	B8	B7	B5	126	[8]	-	O	Output from the RTC 32 kHz ultra-low power oscillator circuit.
Crystal oscillator pins								
XTAL1	D1	C1	B1	12	[8]	-	I	Input to the oscillator circuit and internal clock generator circuits.
XTAL2	E1	D1	C1	13	[8]	-	O	Output from the oscillator amplifier.
Power and ground pins								
USB0_VDDA 3V3_DRIVER	F3	E3	D1	16		-	-	Separate analog 3.3 V power supply for driver.

7.5 AHB multilayer matrix

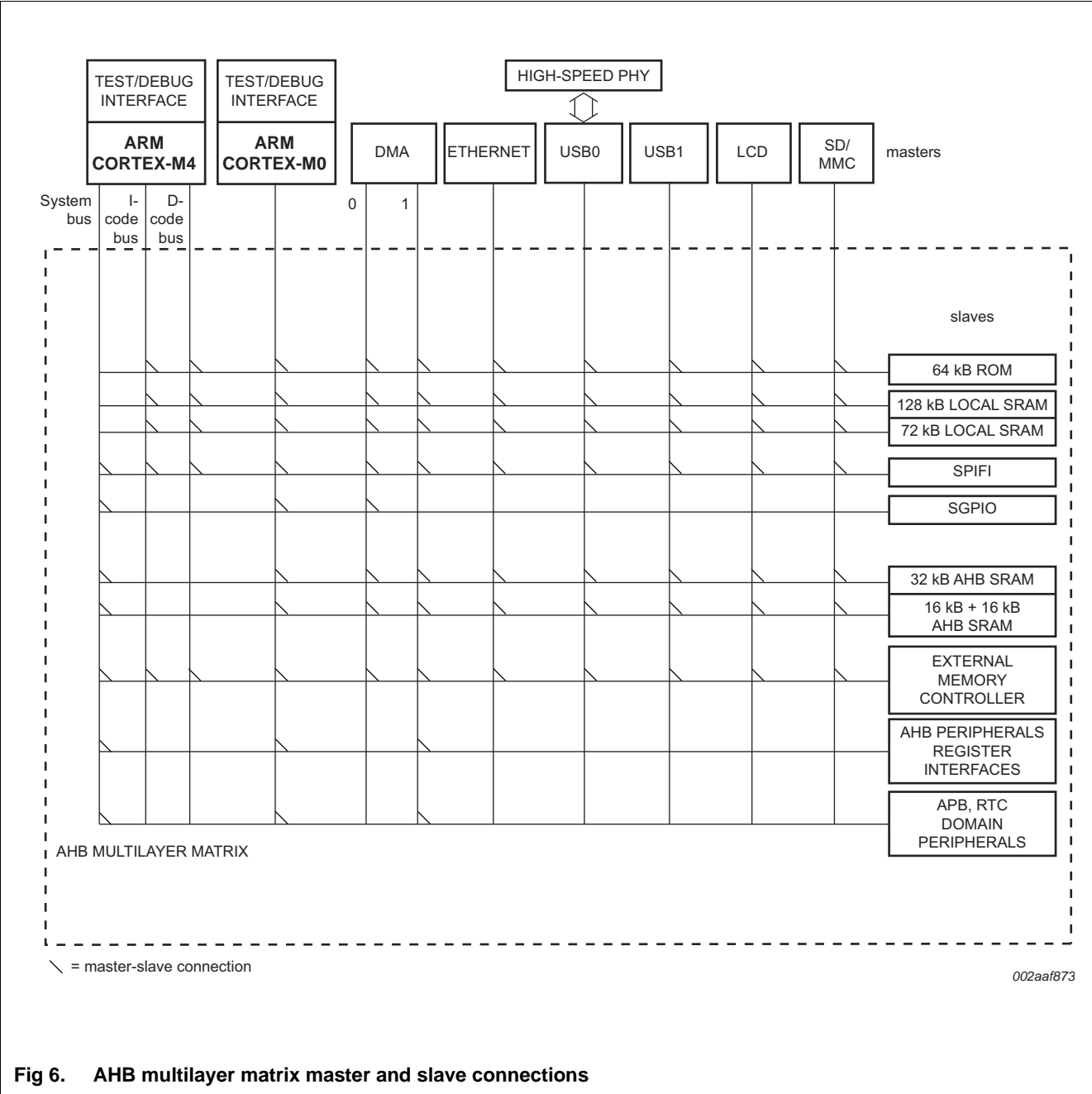


Fig 6. AHB multilayer matrix master and slave connections

7.6 Nested Vectored Interrupt Controller (NVIC)

The NVIC is an integral part of the Cortex-M4. The tight coupling to the CPU allows for low interrupt latency and efficient processing of late arriving interrupts.

The ARM Cortex-M0 co-processor has its own NVIC with 32 vectored interrupts. Most peripheral interrupts are shared between the Cortex-M0 and Cortex-M4 NVICs.

In the two-counter case, the following operational elements are global to the SCTimer/PWM, but the last three can use match conditions from either counter:

- Clock selection
- Inputs
- Events
- Outputs
- Interrupts

7.16.1.1 Features

- Two 16-bit counters or one 32-bit counter.
- Counters clocked by bus clock or selected input.
- Counters can be configured as up-counters or up-down counters.
- State variable allows sequencing across multiple counter cycles.
- Event combines input or output condition and/or counter match in a specified state.
- Events control outputs and interrupts.
- Selected events can limit, halt, start, or stop a counter.
- Supports:
 - up to 8 inputs
 - 16 outputs
 - 16 match/capture registers
 - 16 events
 - 32 states

7.16.2 Serial GPIO (SGPIO)

The Serial GPIOs offer standard GPIO functionality enhanced with features to accelerate serial stream processing.

7.16.2.1 Features

- Each SGPIO input/output slice can be used to perform a serial to parallel or parallel to serial data conversion.
- 16 SGPIO input/output slices each with a 32-bit FIFO that can shift the input value from a pin or an output value to a pin with every cycle of a shift clock.
- Each slice is double-buffered.
- Interrupt is generated on a full FIFO, shift clock, or pattern match.
- Slices can be concatenated to increase buffer size.
- Each slice has a 32-bit pattern match filter.

9. Thermal characteristics

The average chip junction temperature, T_j (°C), can be calculated using the following equation:

$$T_j = T_{amb} + (P_D \times R_{th(j-a)}) \quad (1)$$

- T_{amb} = ambient temperature (°C),
- $R_{th(j-a)}$ = the package junction-to-ambient thermal resistance (°C/W)
- P_D = sum of internal and I/O power dissipation

The internal power dissipation is the product of I_{DD} and V_{DD} . The I/O power dissipation of the I/O pins is often small and many times can be negligible. However it can be significant in some applications.

Table 7. Thermal characteristics

$V_{DD} = 2.2\text{ V to }3.6\text{ V}$; $T_{amb} = -40\text{ °C to }+85\text{ °C}$ unless otherwise specified;

Symbol	Parameter	Min	Typ	Max	Unit
$T_{j(max)}$	maximum junction temperature	-	-	125	°C

Table 8. Thermal resistance (LQFP packages)

Symbol	Parameter	Conditions	Thermal resistance in °C/W ±15 %
			LQFP144
$R_{th(j-a)}$	thermal resistance from junction to ambient	JEDEC (4.5 in × 4 in); still air	38
		Single-layer (4.5 in × 3 in); still air	50
$R_{th(j-c)}$	thermal resistance from junction to case		11

Table 9. Thermal resistance value (BGA packages)

Symbol	Parameter	Conditions	Thermal resistance in °C/W ±15 %		
			LBGA256	TFBGA180	TFBGA100
$R_{th(j-a)}$	thermal resistance from junction to ambient	JEDEC (4.5 in × 4 in); still air	29	38	46
		8-layer (4.5 in × 3 in); still air	24	30	37
$R_{th(j-c)}$	thermal resistance from junction to case		14	11	11

Table 10. Static characteristics ...continued
 $T_{amb} = -40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$, unless otherwise specified.

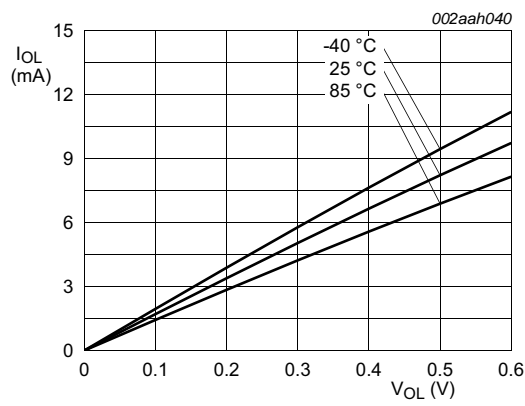
Symbol	Parameter	Conditions		Min	Typ ^[1]	Max	Unit
Oscillator pins							
$V_{i(XTAL1)}$	input voltage on pin XTAL1			-0.5	-	1.2	V
$V_{o(XTAL2)}$	output voltage on pin XTAL2			-0.5	-	1.2	V
C_{io}	input/output capacitance		[17]	-	-	0.8	pF
USB0 pins^[18]							
V_I	input voltage	on pins USB0_DP; USB0_DM; USB0_VBUS $V_{DD(IO)} \geq 2.2\text{ V}$		0	-	5.25	V
		$V_{DD(IO)} = 0\text{ V}$		0	-	3.6	V
R_{pd}	pull-down resistance	on pin USB0_VBUS		48	64	80	k Ω
V_{IC}	common-mode input voltage	high-speed mode		-50	200	500	mV
		full-speed/low-speed mode		800	-	2500	mV
		chirp mode		-50	-	600	mV
$V_{i(dif)}$	differential input voltage			100	400	1100	mV
USB1 pins (USB1_DP/USB1_DM)^[18]							
I_{OZ}	OFF-state output current	$0\text{ V} < V_I < 3.3\text{ V}$	[18]	-	-	± 10	μA
V_{BUS}	bus supply voltage		[19]	-	-	5.25	V
V_{DI}	differential input sensitivity voltage	$ (D+) - (D-) $		0.2	-	-	V
V_{CM}	differential common mode voltage range	includes V_{DI} range		0.8	-	2.5	V
$V_{th(rs)se}$	single-ended receiver switching threshold voltage			0.8	-	2.0	V
V_{OL}	LOW-level output voltage for low-/full-speed	R_L of 1.5 k Ω to 3.6 V		-	-	0.18	V
V_{OH}	HIGH-level output voltage (driven) for low-/full-speed	R_L of 15 k Ω to GND		2.8	-	3.5	V
C_{trans}	transceiver capacitance	pin to GND		-	-	20	pF
Z_{DRV}	driver output impedance for driver which is not high-speed capable	with 33 Ω series resistor; steady state drive	[20]	36	-	44.1	Ω

[1] Typical ratings are not guaranteed. The values listed are at room temperature (25 $^{\circ}\text{C}$), nominal supply voltages.

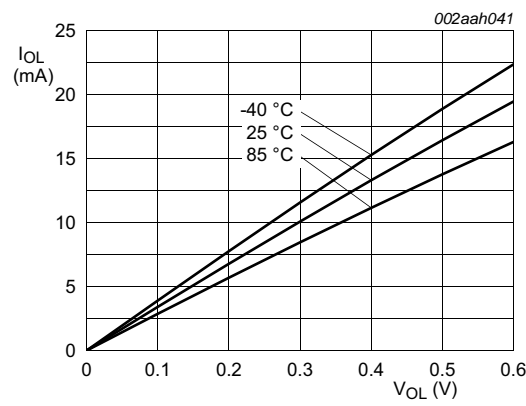
[2] The recommended operating condition for the battery supply is $V_{DD(REG)(3V3)} > V_{BAT} + 0.2\text{ V}$. See Figure 18.

[3] Pin VPP should either be not connected (when OTP does not need to be programmed) or tied to pins VDDIO and VDDREG to ensure the same ramp-up time for both supply voltages.

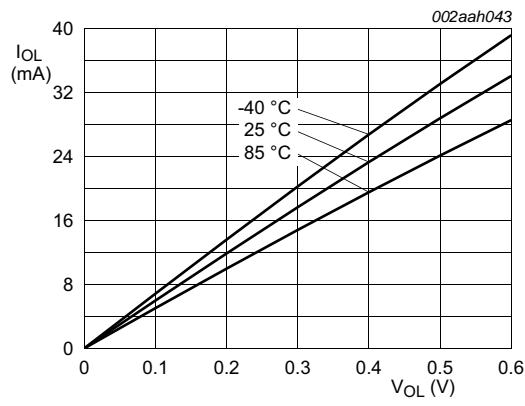
[4] $V_{DD(REG)(3V3)} = 3.3\text{ V}$; $V_{DD(IO)} = 3.3\text{ V}$; $T_{amb} = 25\text{ }^{\circ}\text{C}$.



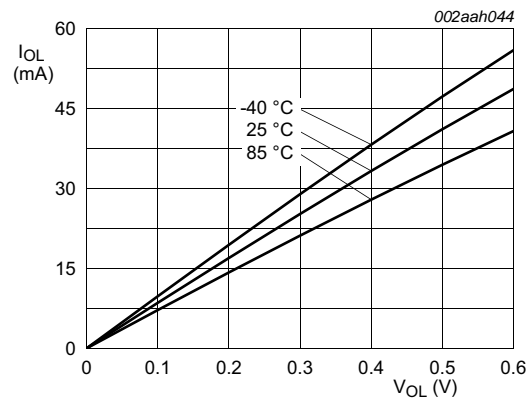
Conditions: $V_{DD(REG)(3V3)} = V_{DD(IO)} = 3.3$ V;
normal-drive; EHD = 0x0.



Conditions: $V_{DD(REG)(3V3)} = V_{DD(IO)} = 3.3$ V;
medium-drive; EHD = 0x1.



Conditions: $V_{DD(REG)(3V3)} = V_{DD(IO)} = 3.3$ V; high-drive;
EHD = 0x2.



Conditions: $V_{DD(REG)(3V3)} = V_{DD(IO)} = 3.3$ V; ultra
high-drive; EHD = 0x3.

Fig 22. High-drive pins; typical LOW level output current I_{OL} versus LOW level output voltage V_{OL}

Table 26. Dynamic characteristics: SGPIO

$T_{amb} = -40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$; $2.2\text{ V} \leq V_{DD(REG)(3V3)} \leq 3.6\text{ V}$; $2.7\text{ V} \leq V_{DD(IO)} \leq 3.6\text{ V}$. Simulated values.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$t_{su(D)}$	data input set-up time			2	-	-	ns
$t_{h(D)}$	data input hold time		[1]	$T_{SGPIO} + 2$	-	-	ns
$t_{su(D)}$	data input set-up time	sampled by SGPIO_CLOCK	[1]	$T_{SGPIO} + 2$	-	-	ns
$t_{h(D)}$	data input hold time	sampled by SGPIO_CLOCK	[1]	$T_{SGPIO} + 2$	-	-	ns
$t_{v(Q)}$	data output valid time		[1]	-	-	$2 \times T_{SGPIO}$	ns
$t_{h(Q)}$	data output hold time		[1]	T_{SGPIO}	-	-	ns
$t_{v(Q)}$	data output valid time	sampled by SGPIO_CLOCK	[1]	-3	-	3	ns
$t_{h(Q)}$	data output hold time	sampled by SGPIO_CLOCK	[1]	-3	-	3	ns

[1] SGPIO_CLOCK is the internally generated SGPIO clock. $T_{SGPIO} = 1/f_{SGPIO_CLOCK}$.

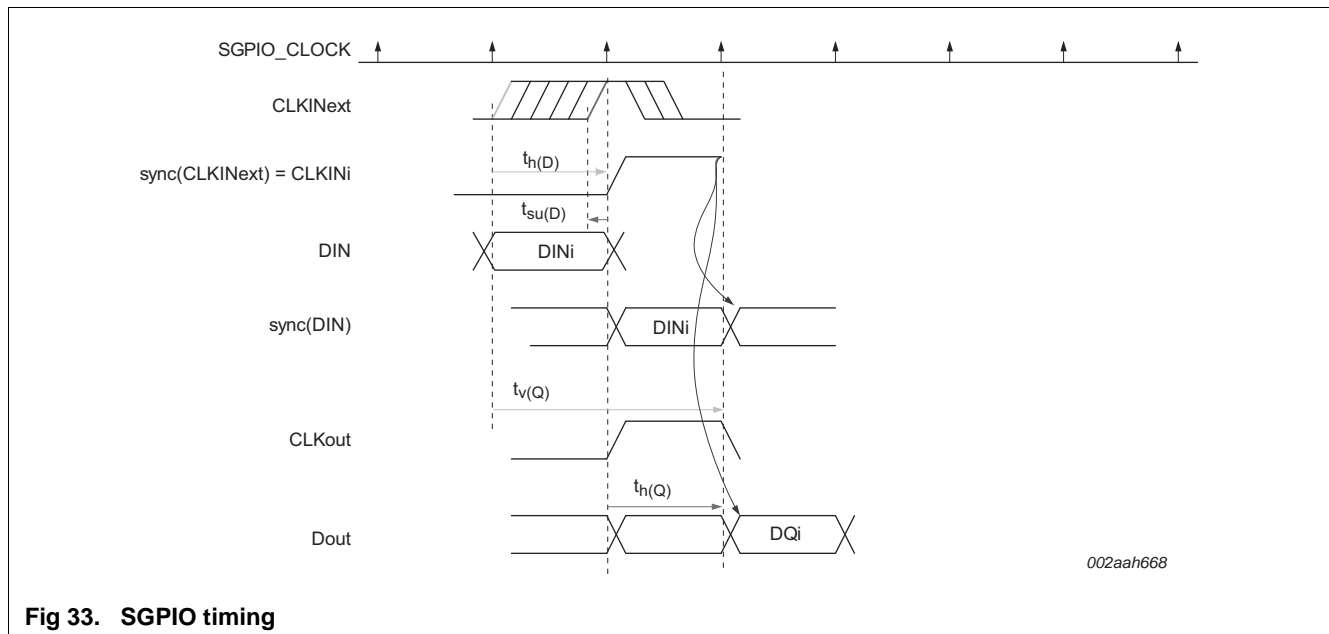


Fig 33. SGPIO timing

11.16 USB interface

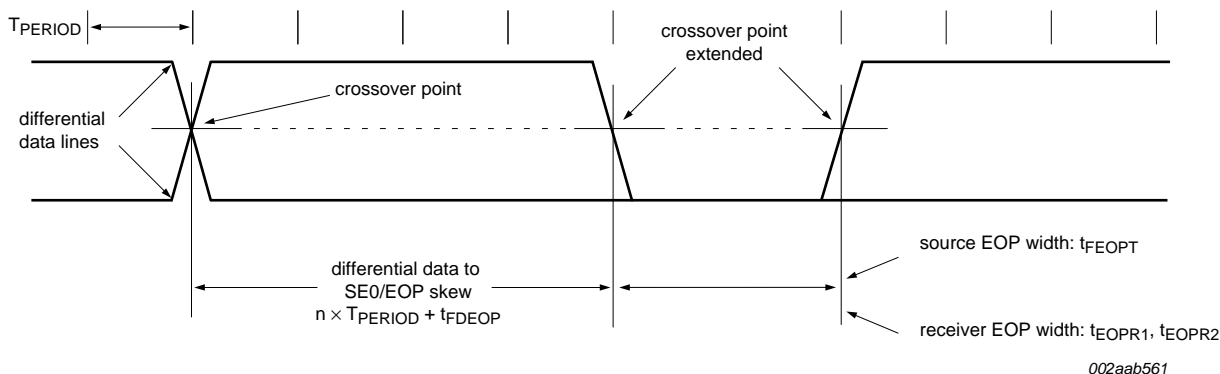
Table 30. Dynamic characteristics: USB0 and USB1 pins (full-speed)

$C_L = 50\text{ pF}$; $R_{pu} = 1.5\text{ k}\Omega$ on D+ to $V_{DD(I/O)}$; $3.0\text{ V} \leq V_{DD(I/O)} \leq 3.6\text{ V}$.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
t_r	rise time	10 % to 90 %		4	-	20	ns
t_f	fall time	10 % to 90 %		4	-	20	ns
t_{FRFM}	differential rise and fall time matching	t_r / t_f		90	-	111.11	%
V_{CRS}	output signal crossover voltage			1.3	-	2.0	V
t_{FEOPT}	source SE0 interval of EOP	see Figure 37		160	-	175	ns
t_{FDEOP}	source jitter for differential transition to SE0 transition	see Figure 37		-2	-	+5	ns
t_{JR1}	receiver jitter to next transition			-18.5	-	+18.5	ns
t_{JR2}	receiver jitter for paired transitions	10 % to 90 %		-9	-	+9	ns
t_{EOPR1}	EOP width at receiver	must reject as EOP; see Figure 37	[1]	40	-	-	ns
t_{EOPR2}	EOP width at receiver	must accept as EOP; see Figure 37	[1]	82	-	-	ns

[1] Characterized but not implemented as production test. Guaranteed by design.

Remark: If only USB0 (HS USB) is used, the pins VDDREG and VDDIO can be at different voltages within the operating range but should have the same ramp up time. If USB1(FS USB) is used, the pins VDDREG and VDDIO should be a minimum of 3.0 V and be tied together.



002aab561

Fig 37. Differential data-to-EOP transition skew and EOP width

15. Soldering

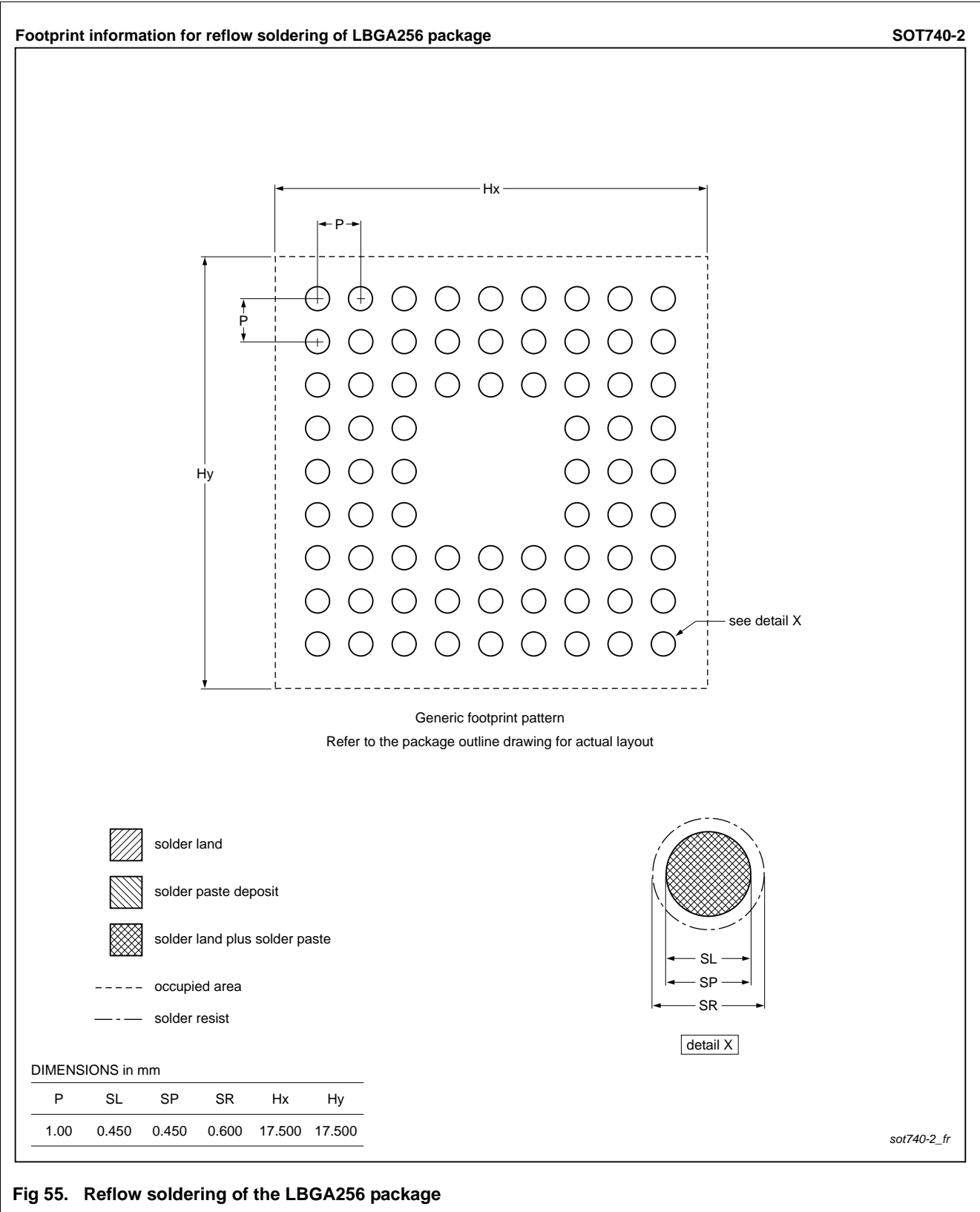


Fig 55. Reflow soldering of the LBG256 package

17. References

- [1] LPC43xx User manual UM10503:
http://www.nxp.com/documents/user_manual/UM10503.pdf
- [2] LPC43X0 Errata sheet:
http://www.nxp.com/documents/errata_sheet/ES_LPC43XX.pdf

Export control — This document as well as the item(s) described herein may be subject to export control regulations. Export might require a prior authorization from competent authorities.

Non-automotive qualified products — Unless this data sheet expressly states that this specific NXP Semiconductors product is automotive qualified, the product is not suitable for automotive use. It is neither qualified nor tested in accordance with automotive testing or application requirements. NXP Semiconductors accepts no liability for inclusion and/or use of non-automotive qualified products in automotive equipment or applications.

In the event that customer uses the product for design-in and use in automotive applications to automotive specifications and standards, customer (a) shall use the product without NXP Semiconductors' warranty of the product for such automotive applications, use and specifications, and (b)

whenever customer uses the product for automotive applications beyond NXP Semiconductors' specifications such use shall be solely at customer's own risk, and (c) customer fully indemnifies NXP Semiconductors for any liability, damages or failed product claims resulting from customer design and use of the product for automotive applications beyond NXP Semiconductors' standard warranty and NXP Semiconductors' product specifications.

19.4 Trademarks

Notice: All referenced brands, product names, service names and trademarks are the property of their respective owners.

I²C-bus — logo is a trademark of NXP B.V.

20. Contact information

For more information, please visit: <http://www.nxp.com>

For sales office addresses, please send an email to: salesaddresses@nxp.com

7.22.6	PLL0AUDIO (for audio)	82	18	Revision history	151
7.22.7	System PLL1	82	19	Legal information	155
7.22.8	Reset Generation Unit (RGU)	82	19.1	Data sheet status	155
7.22.9	Power control	82	19.2	Definitions	155
7.22.10	Power Management Controller (PMC)	83	19.3	Disclaimers	155
7.23	Serial Wire Debug/JTAG	84	19.4	Trademarks	156
8	Limiting values	86	20	Contact information	156
9	Thermal characteristics	87	21	Contents	157
10	Static characteristics	88			
10.1	Power consumption	95			
10.2	Peripheral power consumption	99			
10.3	BOD and band gap static characteristics	101			
10.4	Electrical pin characteristics	102			
11	Dynamic characteristics	106			
11.1	Wake-up times	106			
11.2	External clock for oscillator in slave mode	106			
11.3	Crystal oscillator	107			
11.4	IRC oscillator	107			
11.5	RTC oscillator	107			
11.6	GPCLKIN	108			
11.7	I/O pins	108			
11.8	I ² C-bus	109			
11.9	I ² S-bus interface	110			
11.10	USART interface	111			
11.11	SSP interface	113			
11.12	SPI interface	116			
11.13	SSP/SPI timing diagrams	117			
11.14	SGPIO timing	118			
11.15	External memory interface	120			
11.16	USB interface	125			
11.17	Ethernet	126			
11.18	SD/MMC	128			
11.19	LCD	128			
11.20	SPIFI	129			
12	ADC/DAC electrical characteristics	130			
13	Application information	133			
13.1	LCD panel signal usage	133			
13.2	Crystal oscillator	135			
13.3	RTC oscillator	137			
13.4	XTAL and RTCX Printed Circuit Board (PCB) layout guidelines	137			
13.5	Standard I/O pin configuration	137			
13.6	Reset pin configuration	138			
13.7	Suggested USB interface solutions	138			
14	Package outline	141			
15	Soldering	145			
16	Abbreviations	149			
17	References	150			

Please be aware that important notices concerning this document and the product(s) described herein, have been included in section 'Legal information'.

© NXP Semiconductors N.V. 2016.

All rights reserved.

For more information, please visit: <http://www.nxp.com>

For sales office addresses, please send an email to: salesaddresses@nxp.com

Date of release: 14 March 2016

Document identifier: LPC4350_30_20_10